

CLAIMS

1. An electroless copper plating solution, wherein, along with a first reducing agent, hypophosphorous acid or a hypophosphite is used as a second reducing agent, and a stabilizer to inhibit copper deposition is further used at the same time.
2. An electroless copper plating solution according to Claim 1, which is used to produce a thin film with a thickness of 500 nm or less.
3. An electroless copper plating method, wherein an electroless copper plating solution according to Claim 1 or 2 is used to perform electroless copper plating on a mirror surface whose average surface roughness is less than 10 nm.